

00-689/1D

REMARKS

Claims 1-9 and 19-23 are in the case. Claims 1-2, 4-7, 9, 19, and 21-22 are rejected under 35 USC § 103 over USPN 5,700,735 to Shieue et al. in view of USPN 6,560,862 to Chen et al., and claims 3, 8, 20, and 23 are rejected under 35 USC § 103 over Shieue et al. in view of Chen et al. and further in view of USPN 5,916,823 to Lou et al. Claims 1 and 19 have been amended. No new matter has been introduced by the amendments, which are supported by the disclosure of the original claims and the specification. Reconsideration and allowance of the claims are respectfully requested.

CORRECTION

The attorney's docket number was incorrectly listed as 01-689/1D on the transmittal letter for this application. Applicants respectfully request that the attorney docket number please be corrected to 00-689/1D, which is correctly listed in two places on the first page of the specification.

PRIORITY

The office action states that the specification must indicate the relationship between the instant application and any prior copending application upon which it depends for an earlier effective filing date. Applicants had previously made such an amendment in the application transmittal letter (the second item on the second page of the letter). As the prior pending application has now issued as a patent, applicants hereby amend the first sentence of the application as given above.

CLAIM REJECTIONS UNDER §103

Claims 1-2, 4-7, 9, 19, and 21-22 are rejected over Shieue et al. in view of Chen et al. Independent claim 1 claims, *inter alia*, a bonding pad with *a conductive base layer* having slots formed therein, *an insulating layer* disposed *on top of* the conductive base layer, and *a conductive top layer* disposed *on top of* the insulating layer, where *the conductive base layer and the conductive top layer are not directly physically contacting one another*.

00-689/1D

Shuie et al. do not describe such a bonding pad. Shuie et al. describe a base layer 32 that is a solid layer without any slots in it whatsoever, a top layer 30, and an insulating layer 48 disposed between the two. The vias 36 of Shuie et al. are incorrectly labeled as a slotted base layer in the office action, but they are not configured as a base layer. For example, the insulating layer 48 is not disposed *on top of* the vias 36, which is a requirement for the base layer and the insulating layer in claim 1. Instead, the insulating layer 48 is disposed *around* the vias 36. Applicants have made this more clear by affirmatively stating that the base layer and top layer are not directly physically contacting one another. They may be electrically contacting one another through vias or other such electrical connections which make physical connections between the two layers, but the base layer does not physically touch the top layer.

Chen et al. do not remedy this deficiency of Shuie et al., in that Chen et al. also do not describe a base layer, insulating layer, and top layer that are constructed and disposed as claimed. Thus, claim 1 patentably defines over Shuie et al. in view of Chen et al. Reconsideration and allowance of claim 1 are respectfully requested. Dependent claims 2, 4-7, and 9 depend from independent claim 1, and contain additional important aspects of the invention. Therefore, dependent claims 2, 4-7, and 9 patentably define over Shuie et al. in view of Chen et al. Reconsideration and allowance of dependent claims 2, 4-7, and 9 are respectfully requested.

Similar to that as described above in regard to claim 1, independent claim 19 claims, *inter alia*, an integrated circuit having a bonding pad with *a conductive base layer* having slots formed therein, *an insulating layer* disposed *on top of* the conductive base layer, and *a conductive top layer* disposed *on top of* the insulating layer, where *the conductive base layer and the conductive top layer are not directly physically contacting one another*.

The deficiencies of Shuie et al. in view of Chen et al. in regard to this combination of elements are described above. Thus, claim 19 patentably defines over Shuie et al. in view of Chen et al. Reconsideration and allowance of claim 19 are respectfully requested. Dependent claims 21 and 22 depend from independent claim 19, and contain additional important aspects of the invention. Therefore, dependent claims

00-689/1D

21 and 22 patentably define over Shuie et al. in view of Chen et al. Reconsideration and allowance of dependent claims 21 and 22 are respectfully requested.

Claims 3, 8, 20, and 23 are rejected over Shieue et al. in view of Chen et al. and further in view of Lou et al. Dependent claims 3 and 8 depend from independent claim 1, and therefore claim *inter alia*, a bonding pad with *a conductive base layer* having slots formed therein, *an insulating layer* disposed *on top of* the conductive base layer, and *a conductive top layer* disposed *on top of* the insulating layer, where *the conductive base layer and the conductive top layer are not directly physically contacting one another*.

The deficiencies of Shuie et al. in view of Chen et al. are described above. Lou et al. do not compensate for the deficiencies of Shue et al. and Chen et al., in that Lou et al. also do not describe a base layer, insulating layer, and top layer that are constructed and disposed as claimed. Thus, claims 3 and 8 patentably define over Shuie et al. in view of Chen et al. and further in view of Lou et al. Reconsideration and allowance of claims 3 and 8 are respectfully requested.

Dependent claims 20 and 23 depend from independent claim 19, and therefore claim *inter alia*, an integrated circuit having a bonding pad with *a conductive base layer* having slots formed therein, *an insulating layer* disposed *on top of* the conductive base layer, and *a conductive top layer* disposed *on top of* the insulating layer, where *the conductive base layer and the conductive top layer are not directly physically contacting one another*.

The deficiencies of Shuie et al. in view of Chen et al. are described above. Lou et al. do not compensate for the deficiencies of Shue et al. and Chen et al., in that Lou et al. also do not describe a base layer, insulating layer, and top layer that are constructed and disposed as claimed. Thus, claims 20 and 23 patentably define over Shuie et al. in view of Chen et al. and further in view of Lou et al. Reconsideration and allowance of claims 20 and 23 are respectfully requested.

CONCLUSION

Applicants assert that the claims of the present application patentably define over the prior art made of record and not relied upon for the same reasons as given above. Applicants respectfully submit that a full and complete response to the office action is


00-689/1D

provided herein, and that the application is now fully in condition for allowance. Action in accordance therewith is respectfully requested.

In the event this response is not timely filed, applicants hereby petition for the appropriate extension of time and request that the fee for the extension be charged to deposit account 12-2355. If other fees are required by this amendment, such as fees for additional claims, such fees may be charged to deposit account 12-2252. Should the examiner require further clarification of the invention, it is requested that s/he contact the undersigned before issuing the next office action.

Sincerely,

LUEDEKA, NEELY & GRAHAM, P.C.

By: 

Rick Barnes, 39,596

2004.11.30